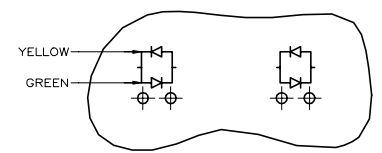
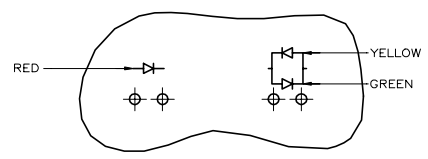


LED CURRENT DIAGRAM  
1116353-7 ONLY  
**OBSOLETE**



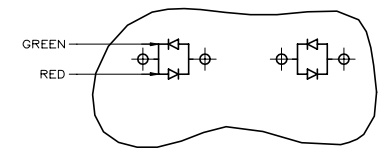
LED CURRENT DIAGRAM  
1116353-8 ONLY  
**OBSOLETE**



LED CURRENT DIAGRAM  
2-1116353-3 ONLY  
**SUPERSEDED**

1. MATERIAL:  
HOUSING - HIGH TEMPERATURE THERMOPLASTIC,  
COLOR: BLACK, UL94V-0  
TERMINALS - 0.36[.014] THICK PHOS BRONZE  
PLATED WITH 3.81µm[.000150] MIN THICK  
BRIGHT TIN LEAD IN SOLDER AREA - 1.27µm[.000050]  
MIN GOLD IN LOCALIZED PLATE AREA. ENTIRE  
TERMINAL PLATED WITH 1.27µm[.000050] MIN  
THICK NICKEL.  
SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY  
PREPLATED WITH 1.27µm[.000050] MIN SATIN  
NICKEL WITH 2.03µm[.000080] MIN TIN POST  
DIPPED ON PCB GROUND TABS  
LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY  
LENS, 0.51 X 0.51[.020 X .020] CARBON STEEL  
WIREFRAME LEADS PLATED WITH 8.89µm[.000350]  
TIN/COPPER OVER 2.03µm[.000080] SILVER OVER  
1.02µm[.000040] NICKEL UNDERPLATE OVER  
2.03µm[.000080] COPPER UNDERPLATE
2. JACK CAVITY CONFORMS TO FCC RULES AND  
REGULATIONS PART 68, SUBPART F.

- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR  
AND TOP PANEL OPENING.
- △ SEE TABLE FOR COLOR OF LEDS AND NUMBER  
REQUIRED.
- 6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT  
IR REFLOW SOLDERING PROCESS COMPATIBLE.
- △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI
- △ MANUFACTURING DATE CODE:  
LOCATED APPROX. AS SHOWN.  
FIRST 2 DIGITS= LAST 2 DIGITS OF YEAR.  
NEXT 2 DIGITS= MANUFACTURING WORK WEEK.  
LAST DIGIT= DAY OF WEEK WITH SUNDAY=1.



LED CURRENT DIAGRAM  
1-1116353-3 ONLY  
**SUPERSEDED  
BY 1-6116353-3**

△ SUPERSEDED BY 2-6116353-8	3.05 [.120]	YELLOW/GREEN	YELLOW/GREEN	2-4416353-8
△ SUPERSEDED BY 2-6116353-4	3.05 [.120]	GREEN	GREEN	2-1116353-4
SUPERSEDED	2.54 [1.00]	RED	YELLOW/GREEN	2-1116353-3
△ SUPERSEDED BY 1-6116353-3	2.54 [1.00]	RED/GREEN	RED/GREEN	1-1116353-3
△ OBSOLETE	2.54 [1.00]	YELLOW/GREEN	YELLOW/GREEN	1-116353-8
△ OBSOLETE	2.54 [1.00]	ORANGE/GREEN	ORANGE/GREEN	1-116353-7
△ OBSOLETE	2.54 [1.00]	YELLOW	YELLOW	1-116353-6
△ OBSOLETE	2.54 [1.00]	GREEN	GREEN	1-116353-5
△ OBSOLETE	2.54 [1.00]	GREEN	YELLOW	1-116353-4
△ OBSOLETE	2.54 [1.00]	YELLOW	-	1-116353-3
△ SUPERSEDED BY 6116353-2	2.54 [1.00]	-	GREEN	1-116353-2
△ OBSOLETE	2.54 [1.00]	YELLOW	GREEN	1-116353-1

RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT  
(COMPONENT SIDE)

SOLDER TAIL LENGTH, DIM A		POSITION 2	POSITION 1	PART NUMBER
INDICATOR COLOR FOR EACH HOUSING				
THIS DRAWING IS A CONTROLLED DOCUMENT. DR: D.L./L.MAYER 08072007 DW: WESTMAN DATE: 108-1163-4 PRODUCT SPEC: INVERTED MODULAR JACK ASSEMBLY, 1X2, SHIELDED, PANEL GROUNDS WITH LEADS DRAWING NO: 114-2154 DATE CODE: 114-2154 DRAWING NO: 114-2154 WEIGHT: 0.000000 APPLICATOR SPEC: 114-2154 MATERIAL: FRESH SEE NOTE 1 CUSTOMER DRAWING SCALE: 4:1 SHEET: 1 OF 1 REV: G4				